Claims

1.A precious metal article comprising a precious metal substrate(1) and a physical vapor deposition layer(2) and a transparent film layer (4) which are sequentially attached to a surface of the precious metal substrate(1), and the transparent film layer (4) formed on the surface of the physical vapor deposition layer (2); wherein the precious metal is gold or silver, wherein the material of the transparent film layer (4) is a fluoride.

2. The precious metal article of claim 1, wherein the precious metal substrate(1) has a gold content of 33-99.99 wt%, preferably 75-99.99wt%, or the precious metal substrate (1) has a silver content of 92.5-99wt%.

3. The precious metal article of claim 1 or 2, wherein the thickness of the physical vapor deposition layer (2) is within a range of 10nm-50um, preferably 0.04um-2um; the material of the physical vapor deposition layer (2) is one or more selected from the group consisting of Ni, Ti, Zn, Cr, Mg, Nb, Sn, Al, In, Fe, Zr, Si, Cu, Ta, Ge, Ag, Co, Au, Gd, La,Y, Ce, W, Hf, Mo, CrN, TiN, TiAICN, TiCN, TiAlN, AlTiN, TiB2, ZrN, FeCo, AlSi, TiSi, CrSi, ZnAl, TiZn, TiAl, TiZr, TiSi, TiNi, NiAl, NiV, NiFe, gold-copper alloy and diamond-like carbon (DLC), and preferably gold-copper alloy.

4. The precious metal article of claim 1 or 2, wherein the precious metal substrate(1) has a surface roughness of 0.001um-50um, preferably 0.005um-0.2um.

5.A method of preparing a precious metal article of any one of claims 1-4 comprising the following step: attaching the physical vapor deposition layer

(2) to a surface of the precious metal substrate(1) by physical vapor deposition.

6. The method of claim 5, wherein the conditions of physical vapor deposition cause that the physical vapor deposition layer (2) has a thickness within a range of 10nm-50um.

7. The method of claim 5, wherein the physical vapor deposition mode is vacuum evaporation plating, vacuum sputtering coating or vacuum ion plating, preferably vacuum ion plating.

8. The method of claim 5, wherein the method further comprises a step of subjecting the surface of the precious metal substrate(1) to a surface treatment, such that the precious metal substrate (1) has a surface roughness within a range of 0.001um-50um, preferably 0.005um-0.2um.

9. The method of claim 8, wherein the method further comprises rinsing the surface-treated precious metal substrate(1) by means of the following modes: ultrasonically washing the precious metal substrate(1) under the ultrasonic frequency condition of 20-30kHz for 1-15min, and/or cleaning a surface of the precious metal substrate(1) with 95-98 wt% of alcohol.

10. The method of claim 9, wherein the method further comprises a step of baking the ultrasonically treated precious metal substrate(1), the baking temperature is 100-150℃, and the baking time is 5-30min.